

# Overview of the X-ray Astronomical Imaging Detectors - CCD to APS -

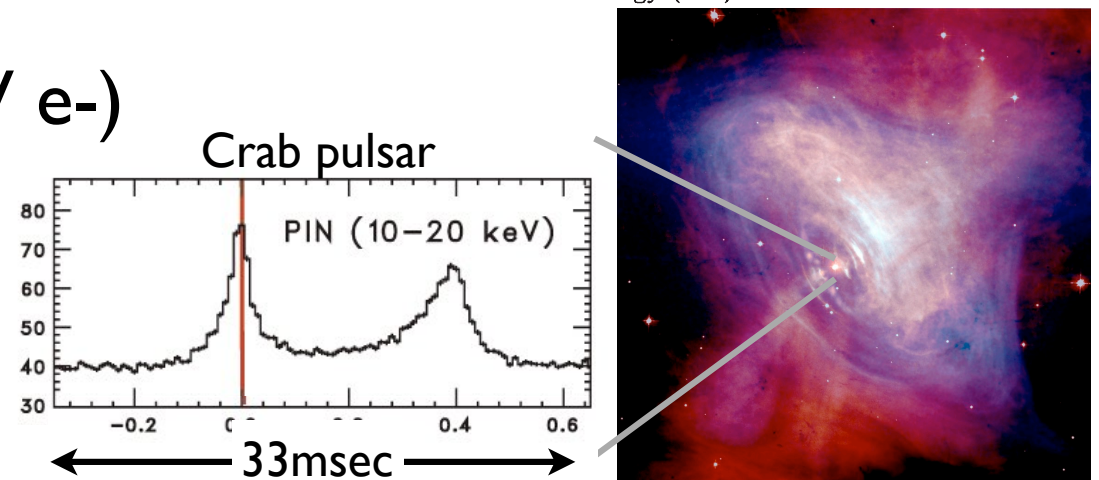
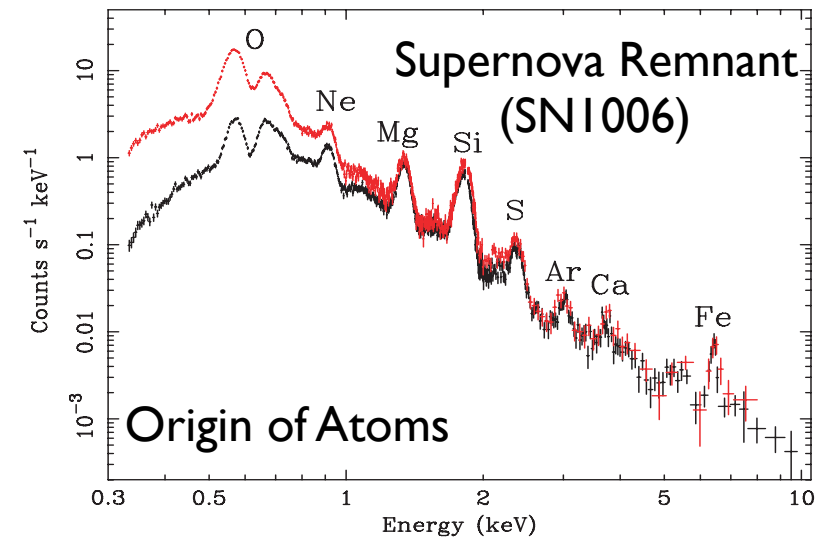
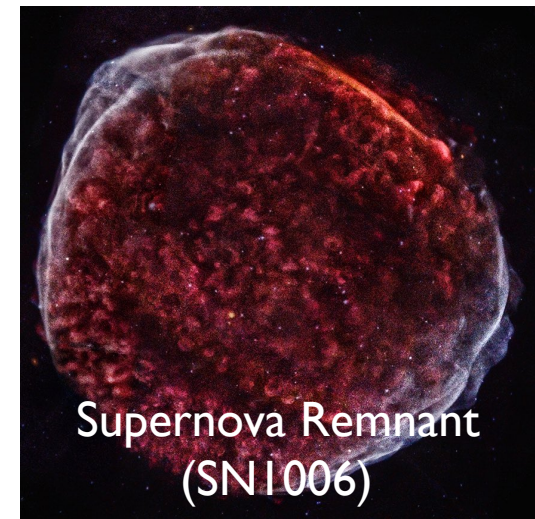
Takeshi Go TSURU (Kyoto U.)  
2017 Dec 11 @ SOIPIX2017/HSTD11

# Outline

- Some Intro. Overview of Imaging System
- X-ray CCD for  $< 10$  keV band
- CCD with Parallel Readout
- CMOS APS, Hybrid
- CdTe / CdZnTe
- X-ray SOIPIX (our development)

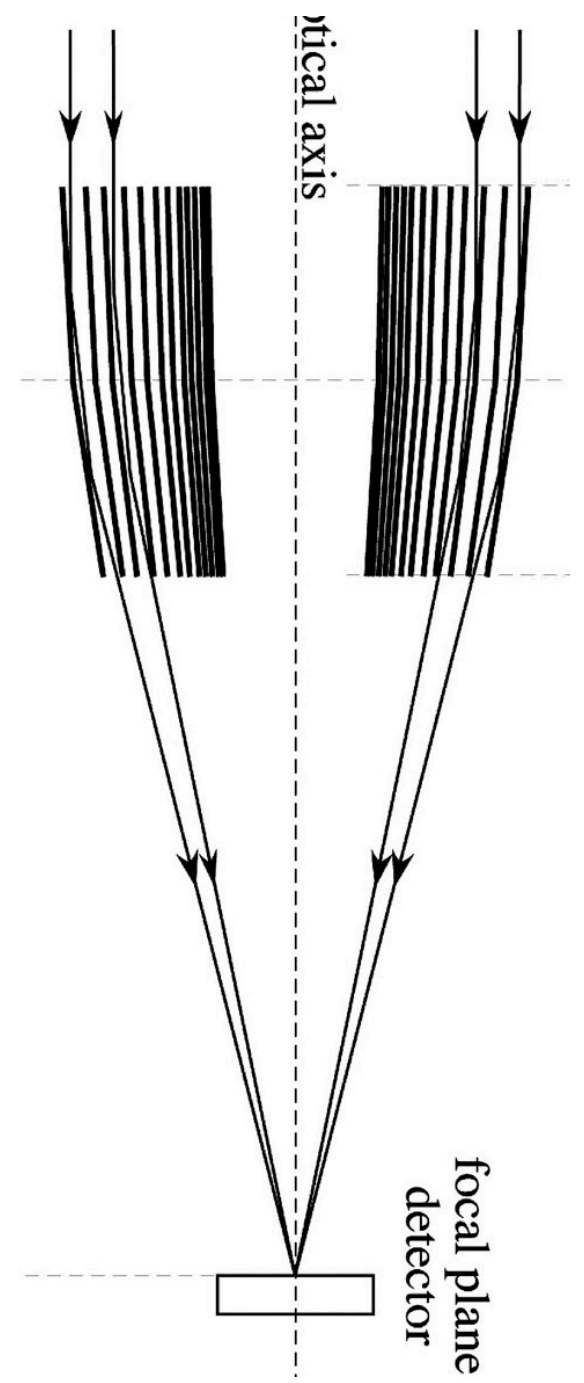
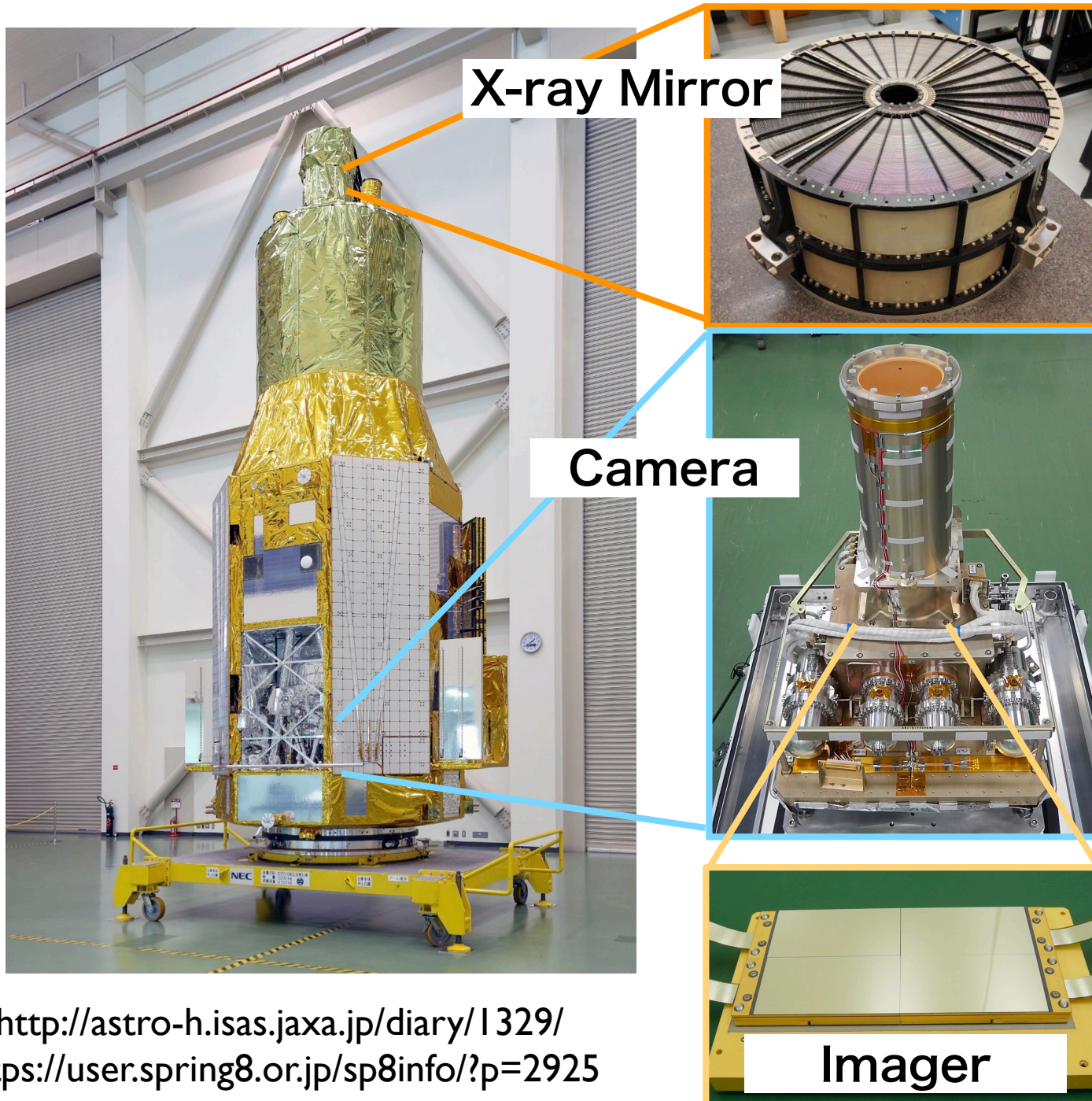
# What is necessary for X-ray Astronomy

- Imaging
  - Fine structure of diffuse sources
  - Faint sources
- Spectroscopy
  - Temperature
  - Abundances of Elements
  - Doppler Velocity
- Wide X-ray Energy band
  - Absorbed sources
  - Non-thermal emission (e.g. Synchrotron from TeV e<sup>-</sup>)
- Timing
  - Pulsation and Burst



<http://chandra.harvard.edu/photo/2013/sn1006/>  
[http://hubblesite.org/image/1248/news\\_release/2002-24](http://hubblesite.org/image/1248/news_release/2002-24)

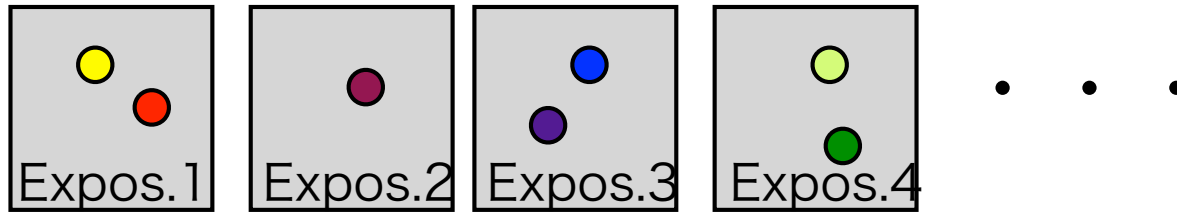
# X-ray Imaging System



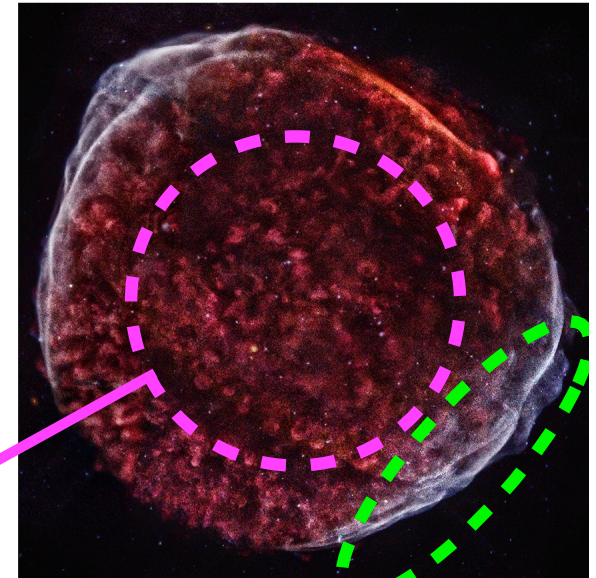
<http://astro-h.isas.jaxa.jp/diary/1329/>  
<https://user.spring8.or.jp/sp8info/?p=2925>



# X-ray Photon Counting



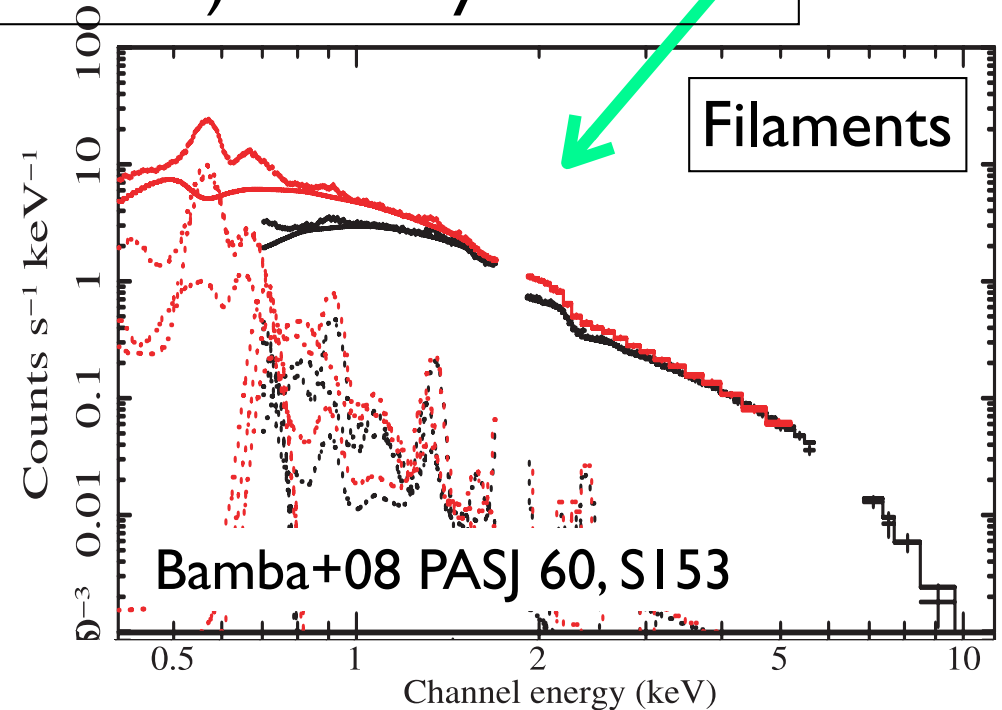
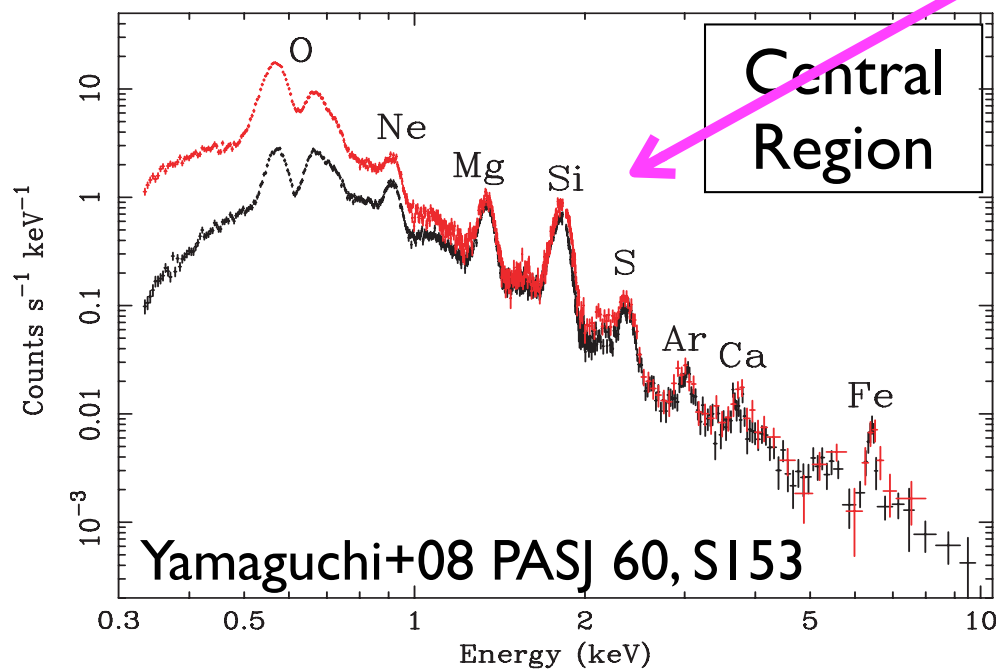
- Detect an X-ray photon as one-by-one event.
- Measure position, energy and time of each X-ray event.
- Make exposures of  $\sim 10^4$  times.



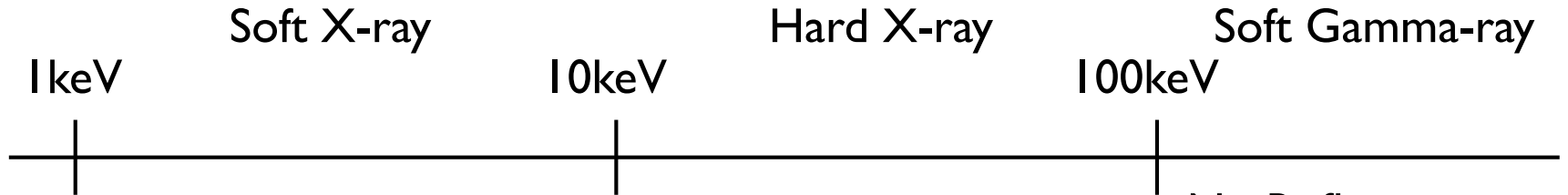
<http://chandra.harvard.edu/photo/2013/sn1006/>

Map of the number of X-ray events

Histogram of energy (electron number) of X-ray events

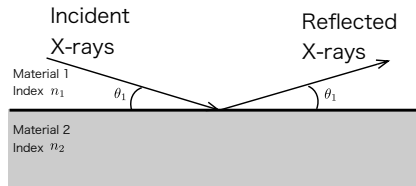


# Overview of Imaging System

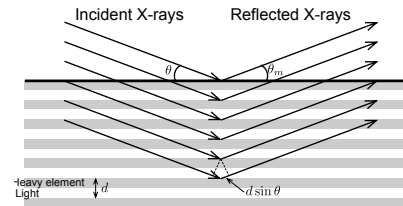


Optics

Total Reflection  
Single layer Mirror



Bragg reflection  
Multilayer Mirror



No Reflection  
Coded Mask  
Compton Camera

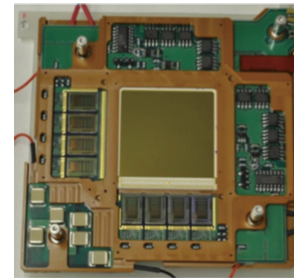


Semiconductor  
Imager

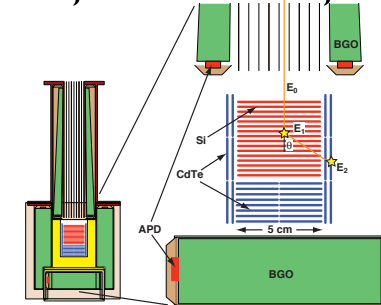
Si



CdTe/CZT



Si, CdTe/CZT, Ge



Detection

Photoabsorption

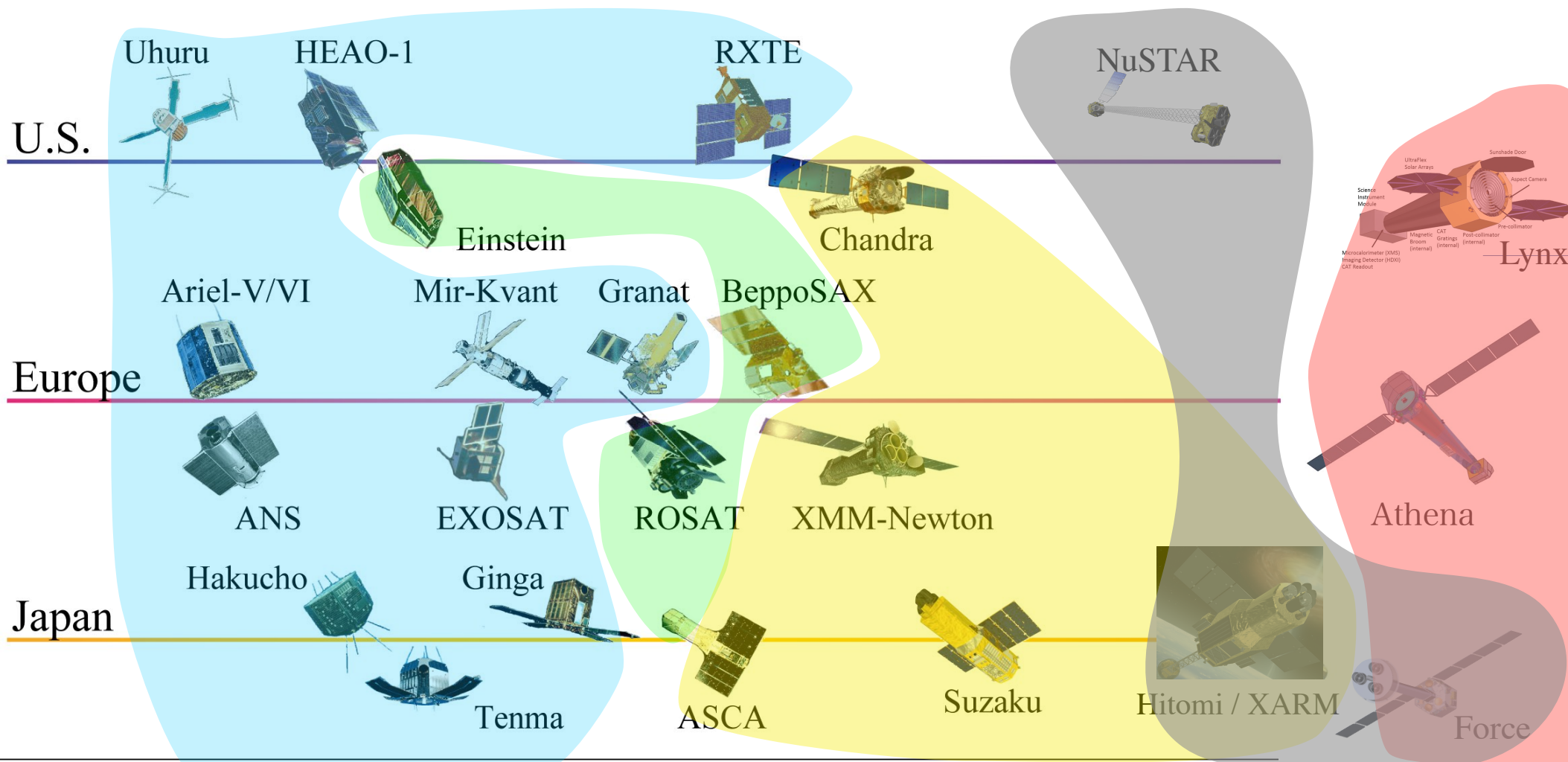
Photoabsorption  
Compton Scattering

Background

Cosmic X-ray Background  
(Unresolved Faint Sources)

Non X-ray Background  
(High Energy Particle)

# Major X-ray Astronomical Satellites



Collimator

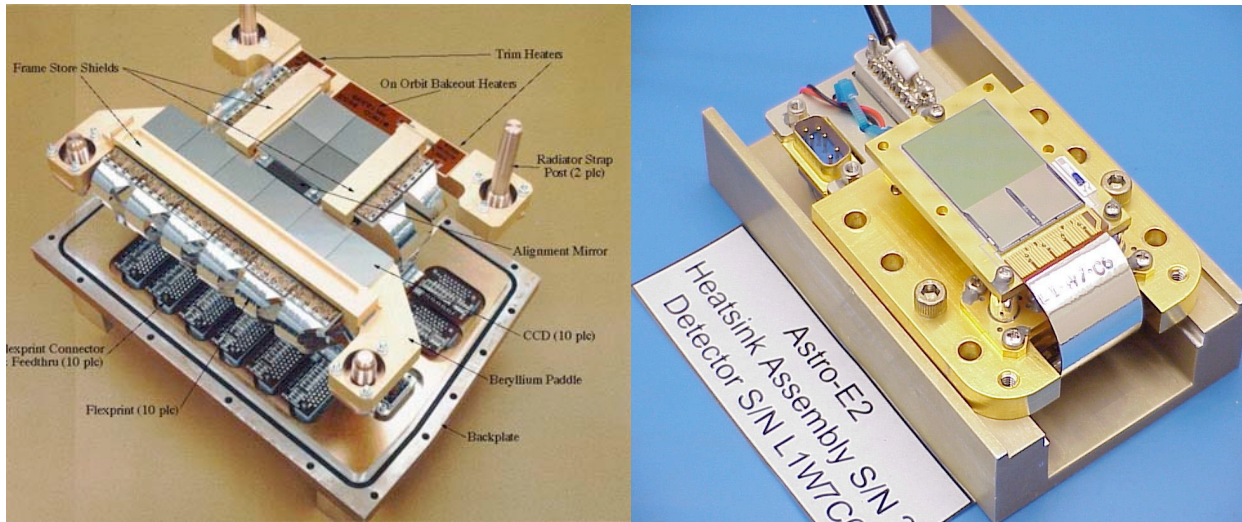
Gas Imager

CCD Imager

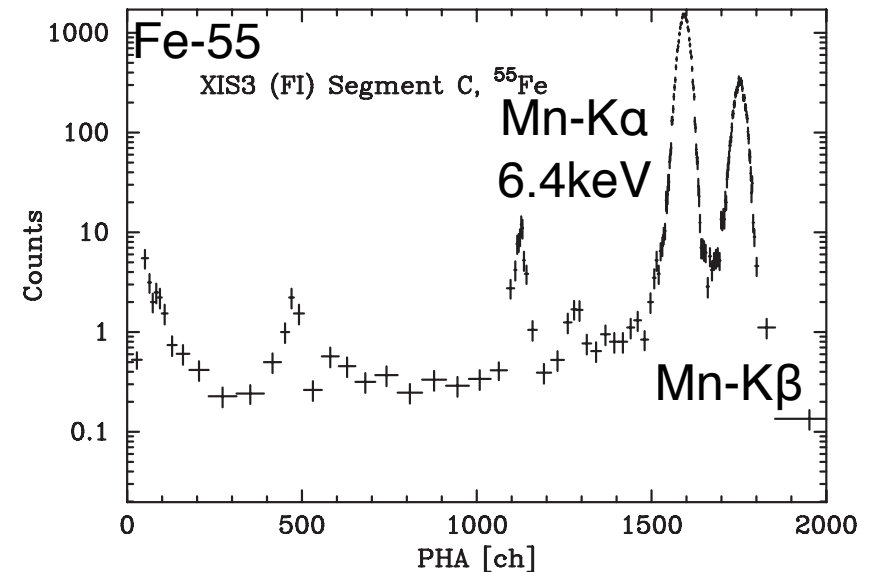
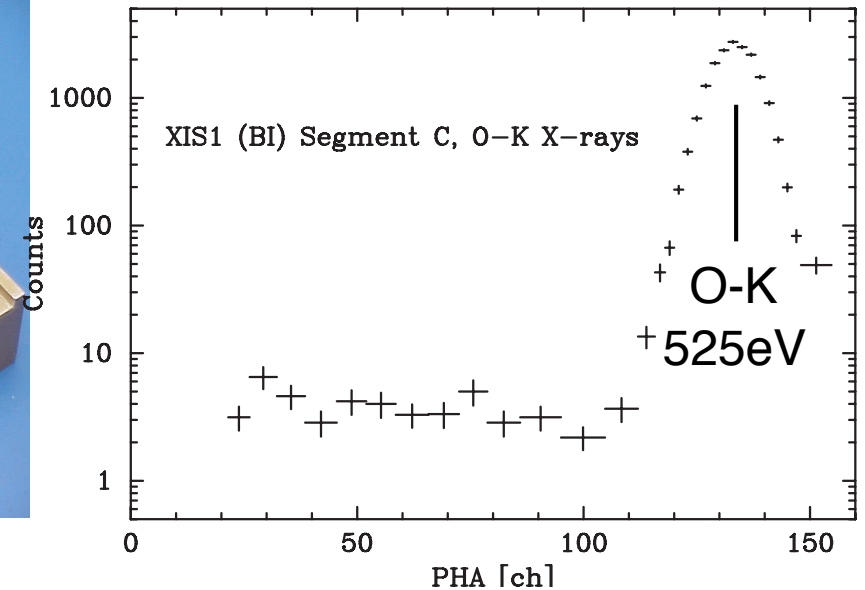
High Speed  
CCD, APS

CdTe/GZT

# CCD cameras of Chandra (ACIS) & Suzaku (XIS)



- CCDs of MIT Lincoln Lab.
  - Depletion 65 $\mu\text{m}$  for FI, 42 $\mu\text{m}$  for BI
  - Pixel size 24 $\mu\text{m}$  $\times$ 24 $\mu\text{m}$ , Format 1K $\times$ 1K
  - ENC  $\sim$ 3e (rms), 135eV (FWHM) at 6keV
- Proton irradiation produces displacement damage in silicon
  - Reduce Charge Transfer Efficiency (CTE)
  - Degrade spectral performance.

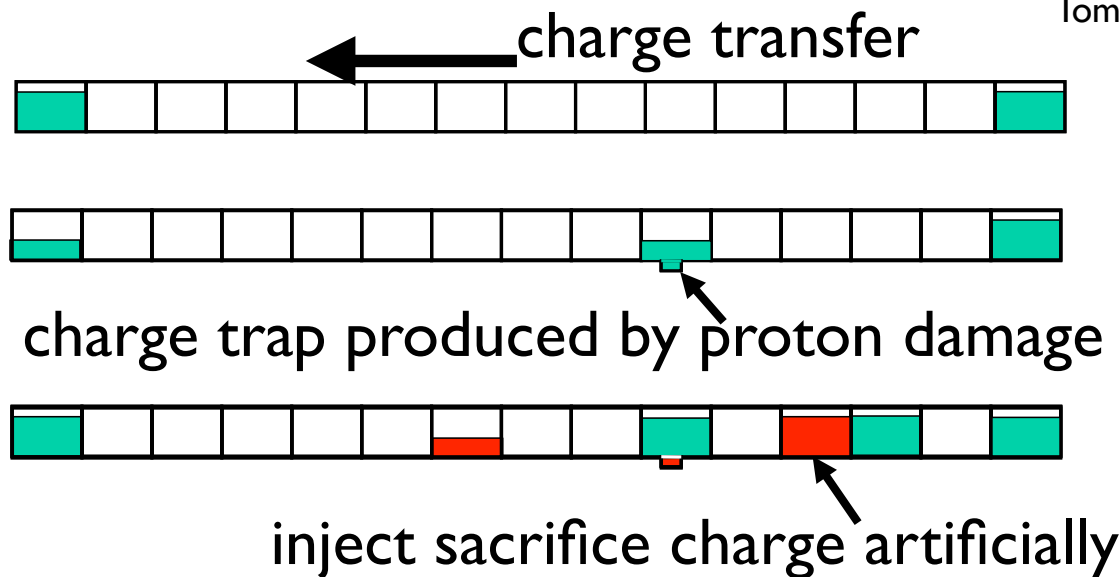




# Charge Injection to Recover CTE

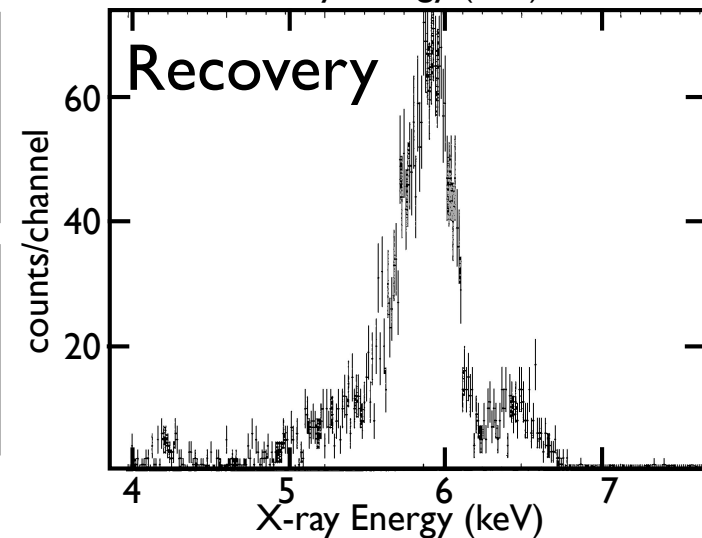
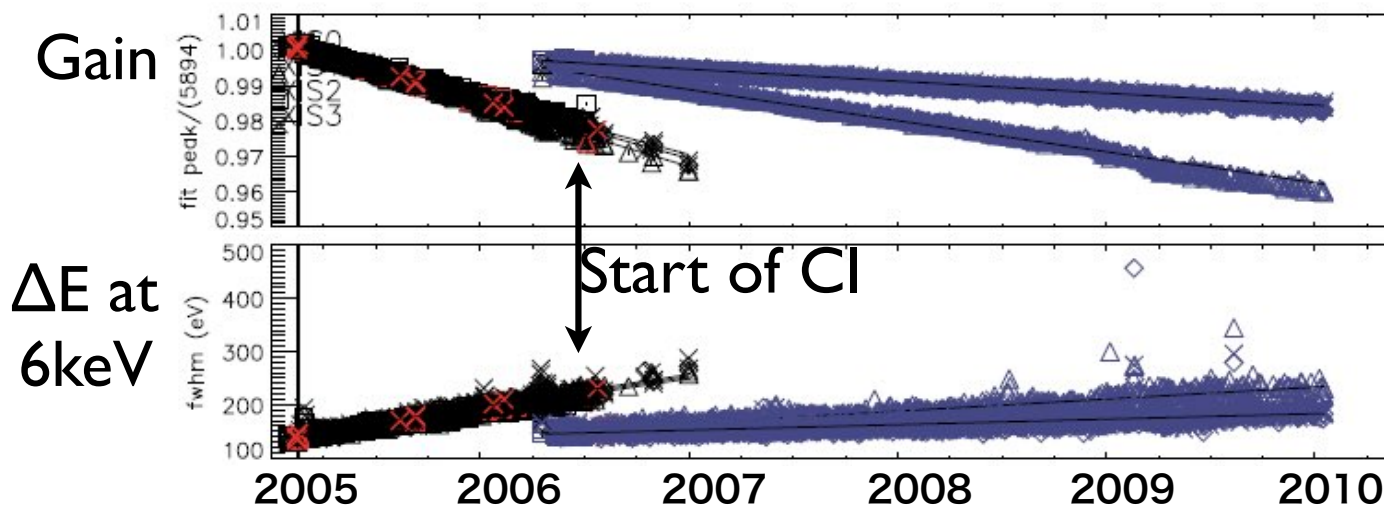
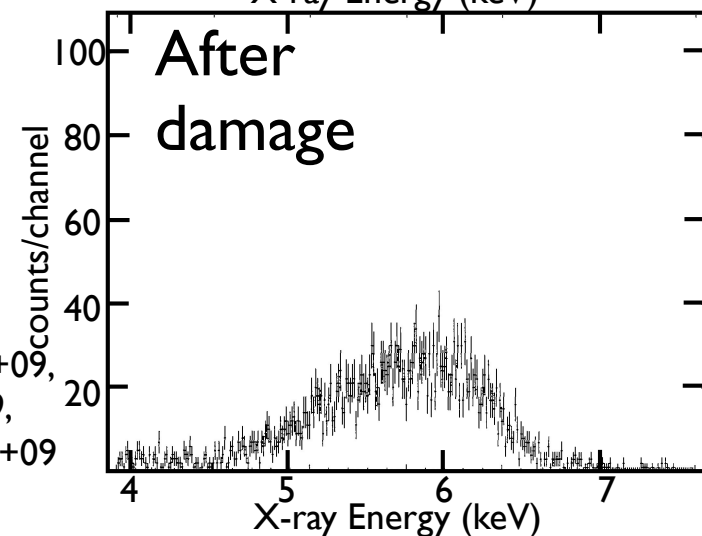
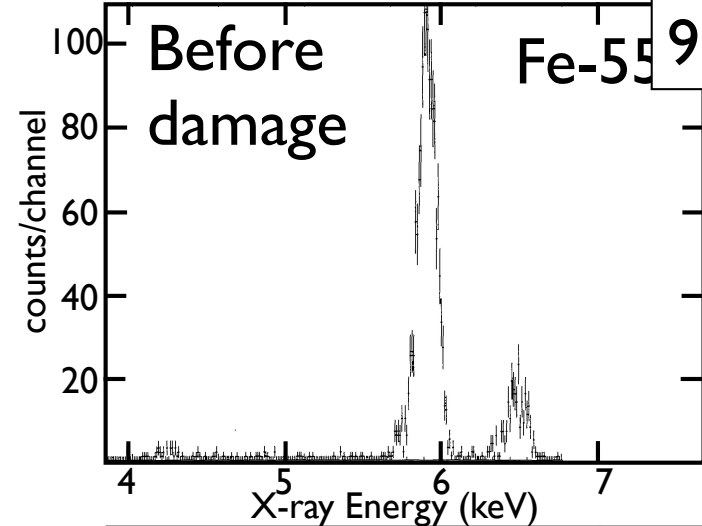
## Proton damage and recovery experiment

Tomida, TT+97

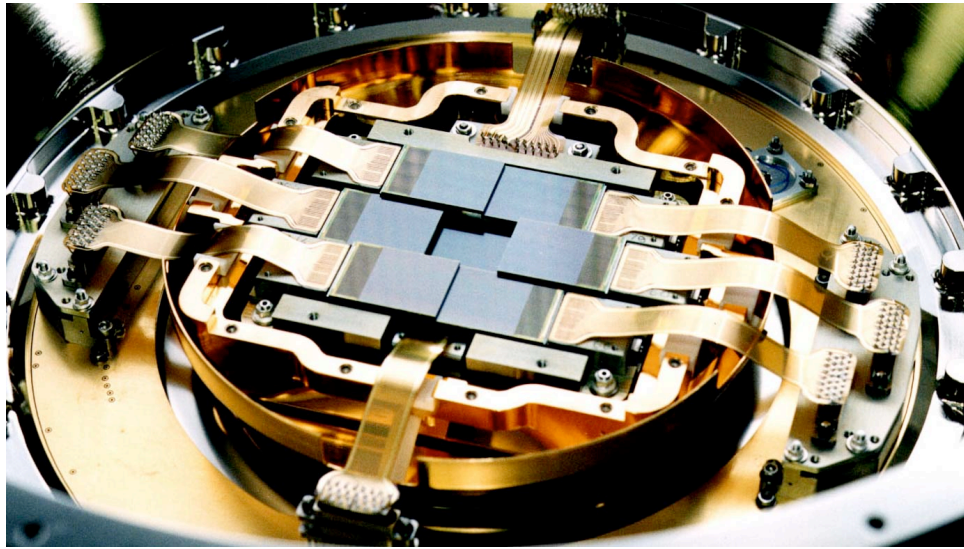


Suzaku realized the charge injection technique in orbit for the first time.

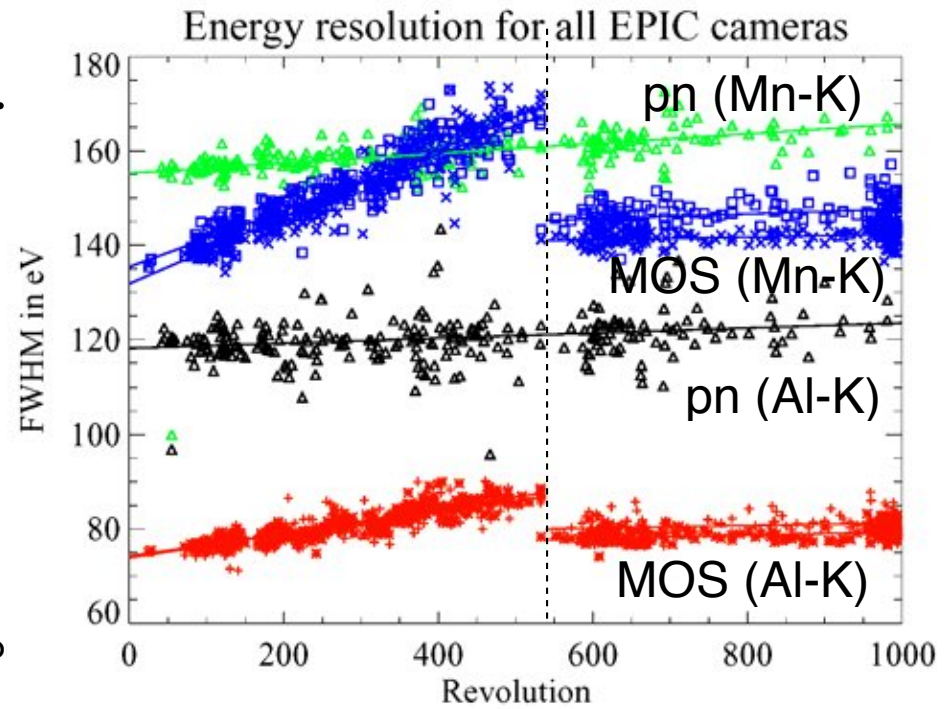
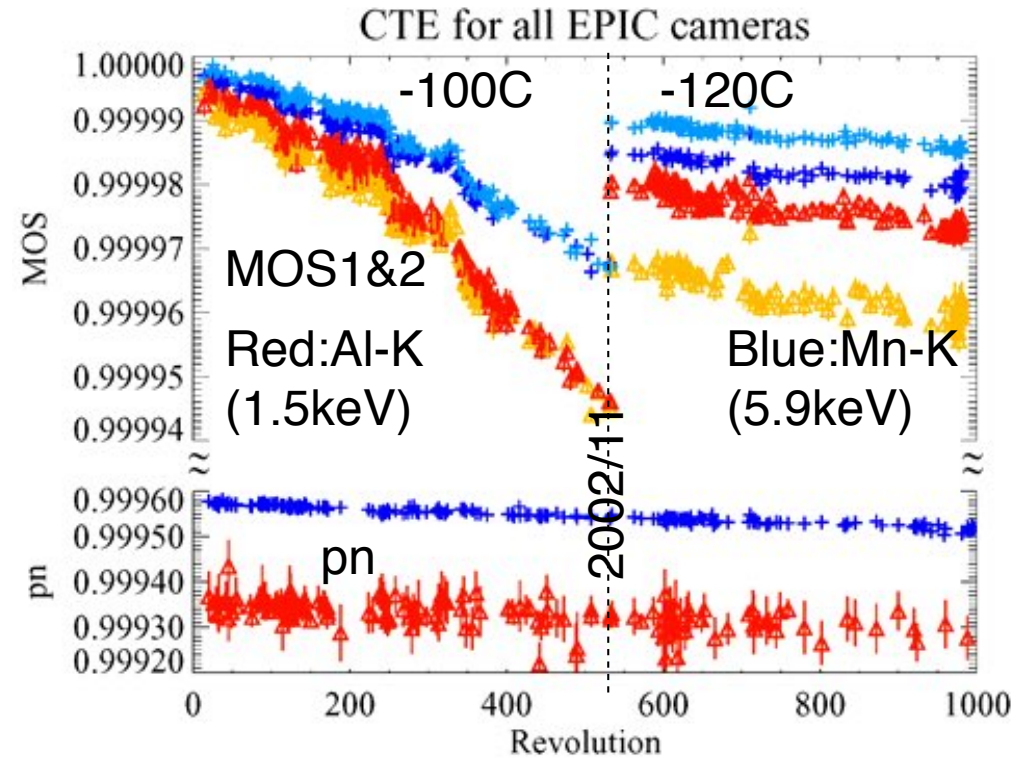
Uchiyama, TT+09,  
Ozawa, TT+09,  
Nakasjima, TT+09  
etc



# EPIC-MOS of XMM-Newton - Low Temp. to Recover CTE

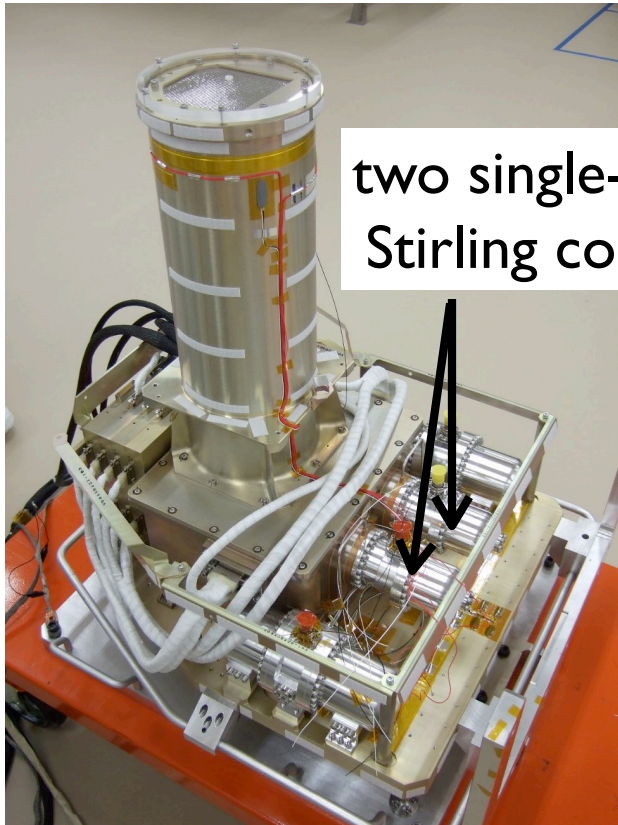


- Leicester U., EEV (Teledyne e2V)
  - Pixel size  $40\mu\text{m}^2$ , Format  $600\times 600$
  - Depletion  $35\mu\text{m}$ . FI with Open-electrode structure for high QE at a low energy band.
  - ENC  $\sim 3e$  (rms),  $135\text{eV}$  (FWHM) at  $6\text{keV}$
- Recover CTE by cooling the sensor to  $-120\text{C}$ .
  - Make de-trapping time longer  $\Rightarrow$  traps stay full for a long time.
  - Once the traps are filled, signal charge can be transferred without loss.

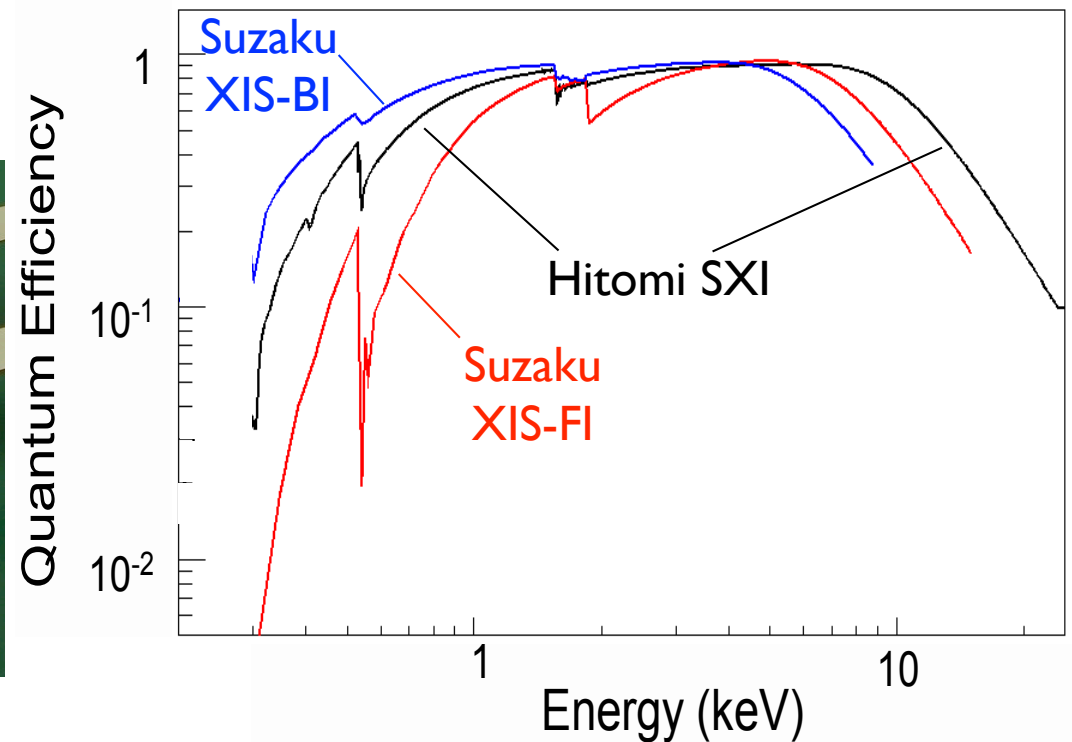
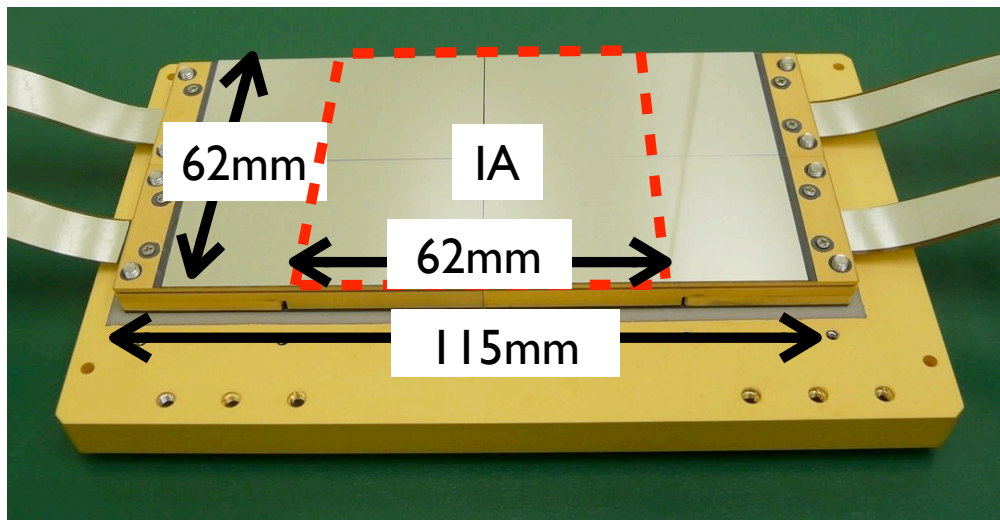




# CCD of Hitomi (SXI) - BI with a Thick Depletion

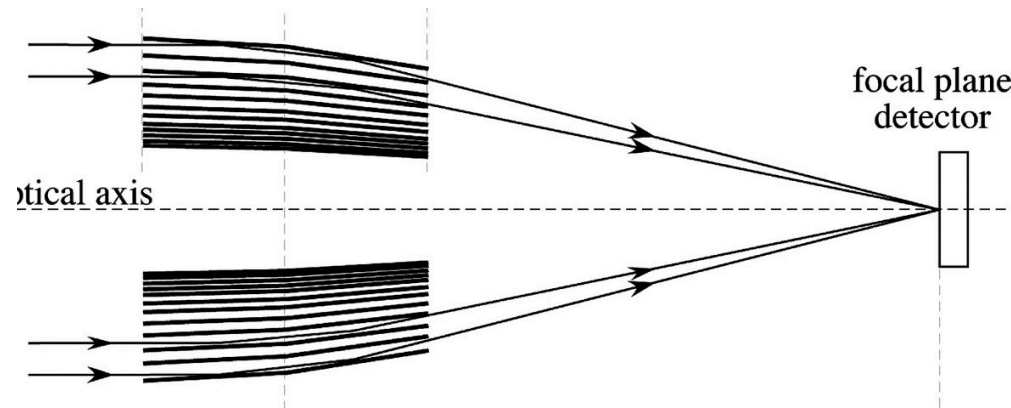


- Osaka U., Kyoto U., ISAS. Hamamatsu
- Pixel Size  $24\mu\text{m}$ , Format  $1280 \times 1280$ .  $2 \times 2$  array.
- BI with  $200\mu\text{m}$  depletion by using N-type wafer with  $>10\text{k}\Omega\text{cm}$  so that we obtain high QE at both of high and low energy bands.
- On-chip Al coating to block optical light
- Charge Injection and Cool down to  $-120^\circ\text{C}$  by using Stirling coolers



# Limitation due to low time resolution of CCD (~1sec)

- Unable to make good use of the performance of large collecting area and high angular resolution of the latest mirrors.
  - Event pileup occurs. Photon counting is impossible.



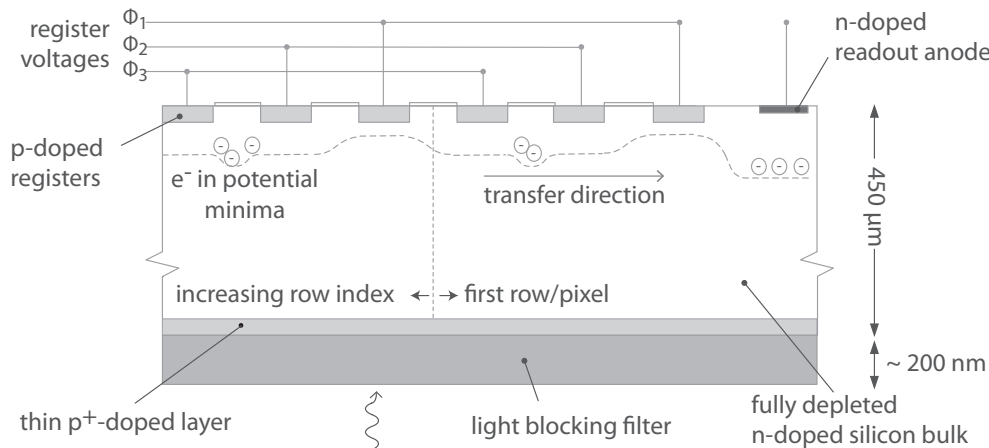
- Unable to resolve fast variability of compact objects such as blackholes and neutron stars.
- Unable to apply anti-coincidence technique
  - Unable to make use of the excellent performance of Si in the band above 10keV due to the high particle background

**High Frame Rate and High Time Resolution are Key Issues for Next Generation of X-ray Astronomical Imagers below 10keV**



# CCD with Parallel Readout

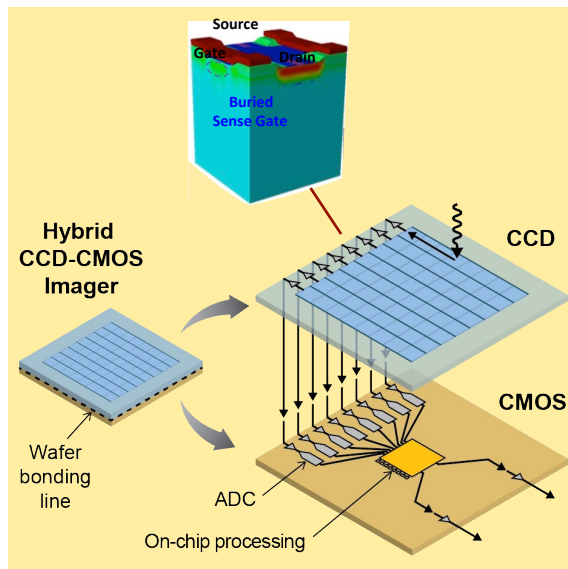
## pn-CCD (MPE, PNSensor)



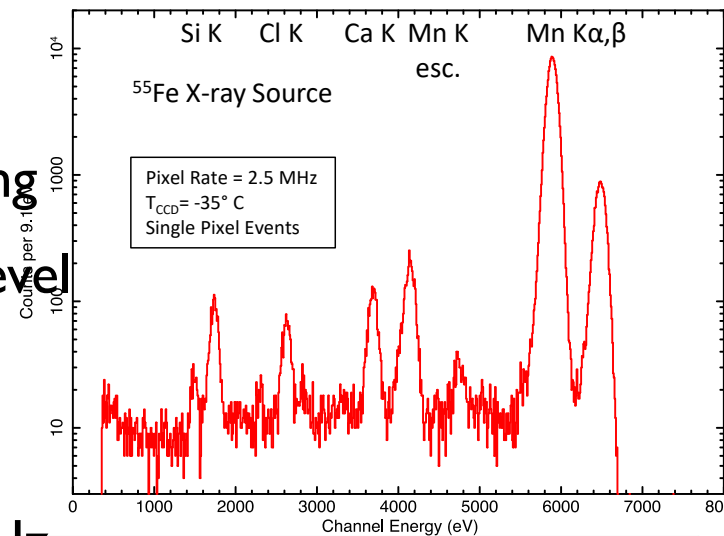
- Transfer registers are formed by pn-junctions.
- XMM-Newton, eROSITA
- Pixel Size 75μm, Depletion 450μm
- Exposure 50msec, Readout 9.2msec for 384×384 pixels (24μsec/row).
- 140 eV (FWHM) at 6keV

2014MeidingerSPIE\_Report on the eROSITA camera system.pdf

## Digital CCD (MIT Lincoln Lab.)



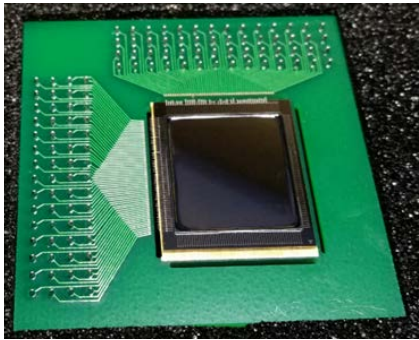
- CCD-to-CMOS integration via tight-pitch wafer-to-wafer bonding
- CMOS-compatible CCD clock level of +1.1 to -0.9V. Low-power
- Low ENC with high pixel rate
  - 6.4e @ 1.25MHz, 10e @ 5MHz
- Pixel Size 8μm



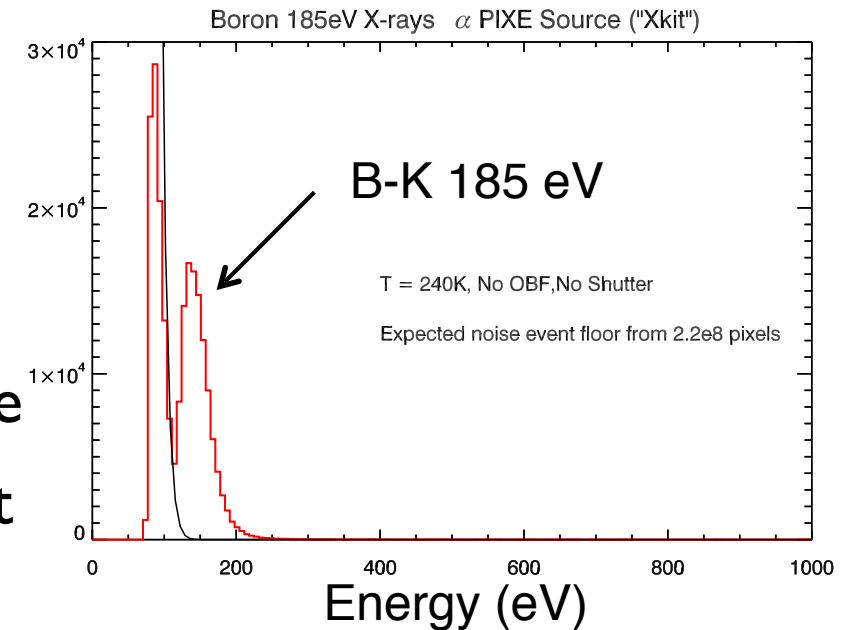
143 eV (RWHM) for 6keV X-ray @ 2.5MHz

# No charge transfer. CMOS, APS

## Monolithic bulk CMOS (SAO/Sarnoff)

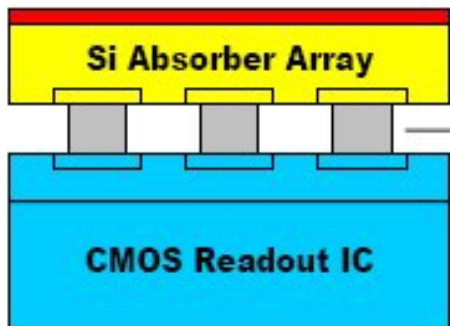


- Pixel Size  $16\mu\text{m}$ , depletion  $10\sim 15\mu\text{m}$
- 6 Transistor Pinned Photo Diode pixels with  $\sim 135\mu\text{V}/\text{e}$
- Low ENC  $\sim 3\text{e}$  (rms), B-K at  $185\text{eV}$  is detected

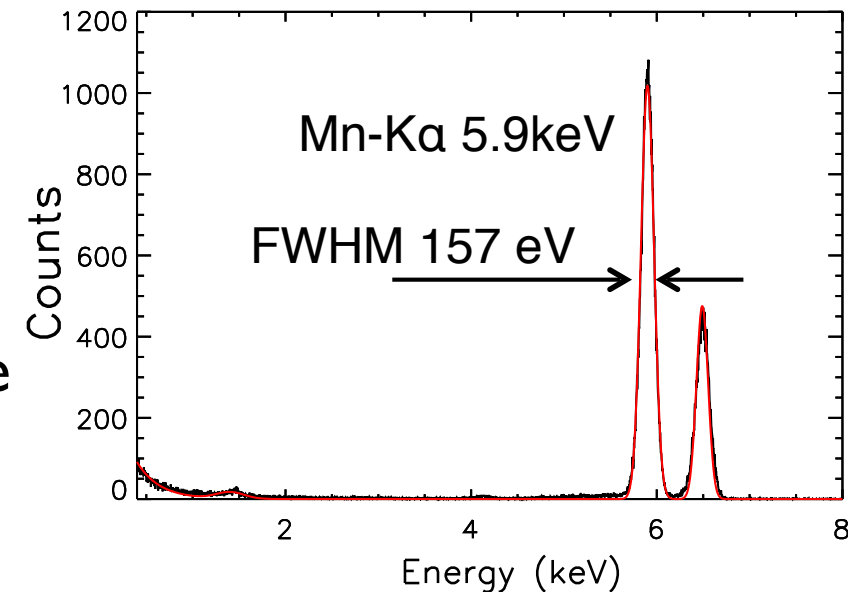
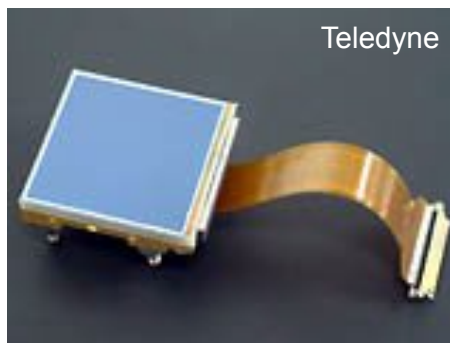


2017KenterSPIE\_Advancing the technology of monolithic CMOS detectors for use as x-ray imaging spectrometers

## Si Hybrid sensor (PSU/Teledyne)

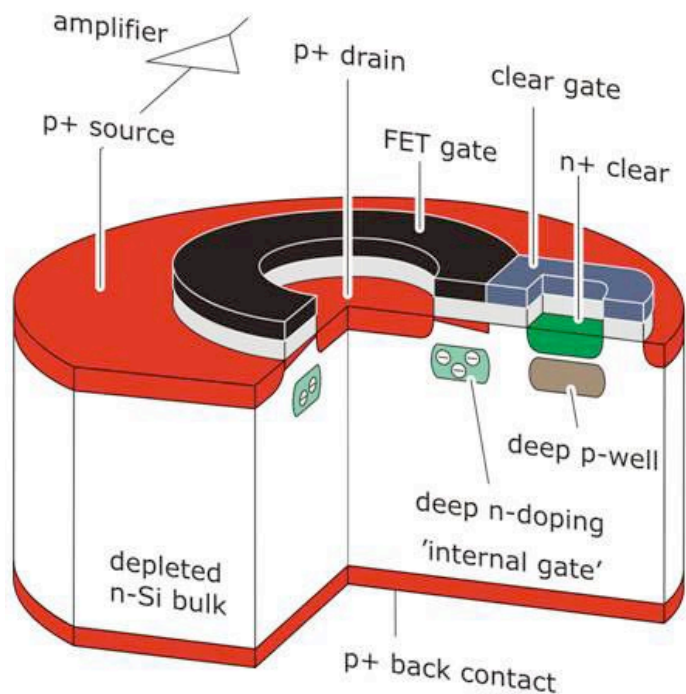


- Si sensor array and readout array bump-bonded together.
- Based on IR detector technology with heritage from JWST
- Pixel Size  $12.5 \sim 36\mu\text{m}$ , depletion  $200\mu\text{m}$

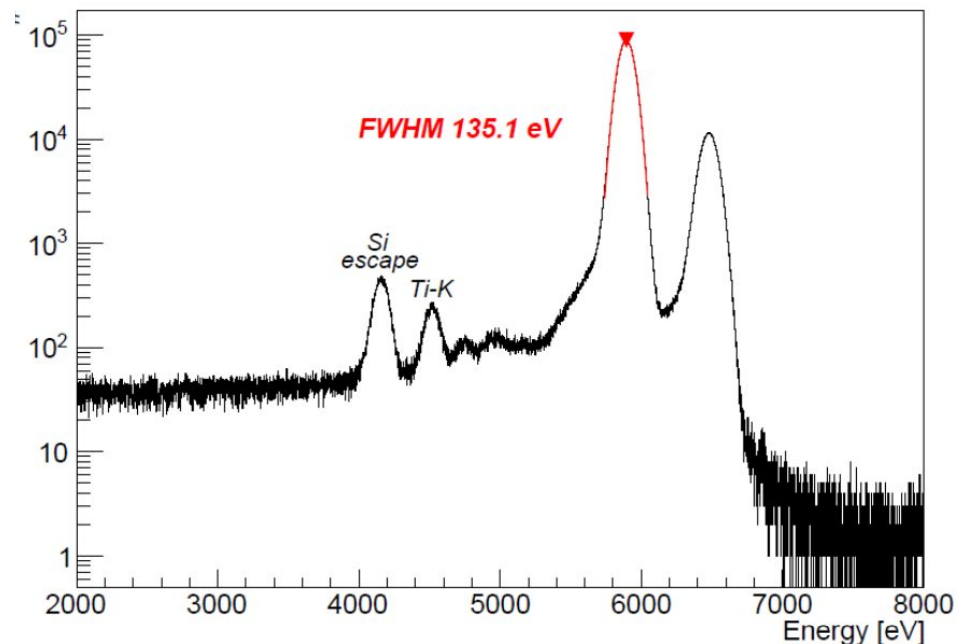
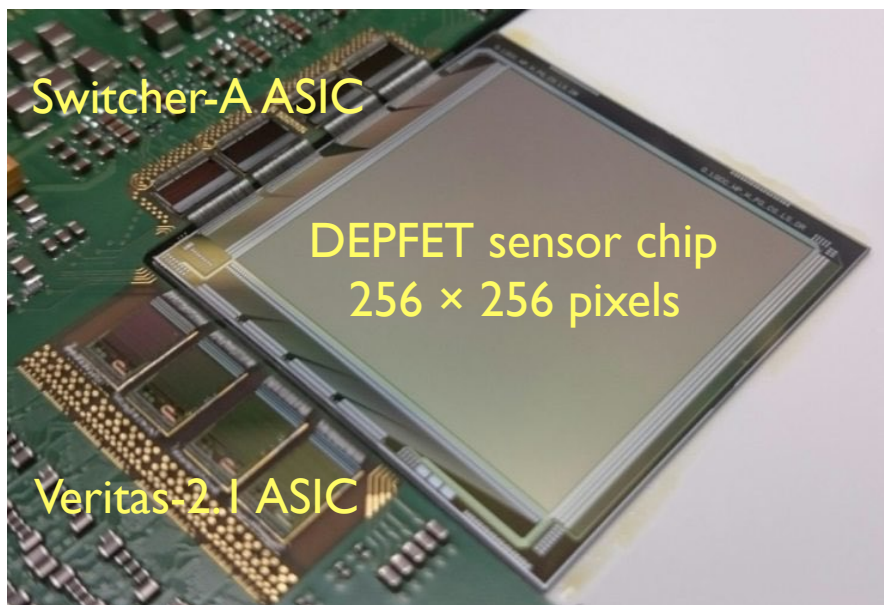


2017HullSPIE\_Recent X-ray hybrid CMOS detector developments and measurements

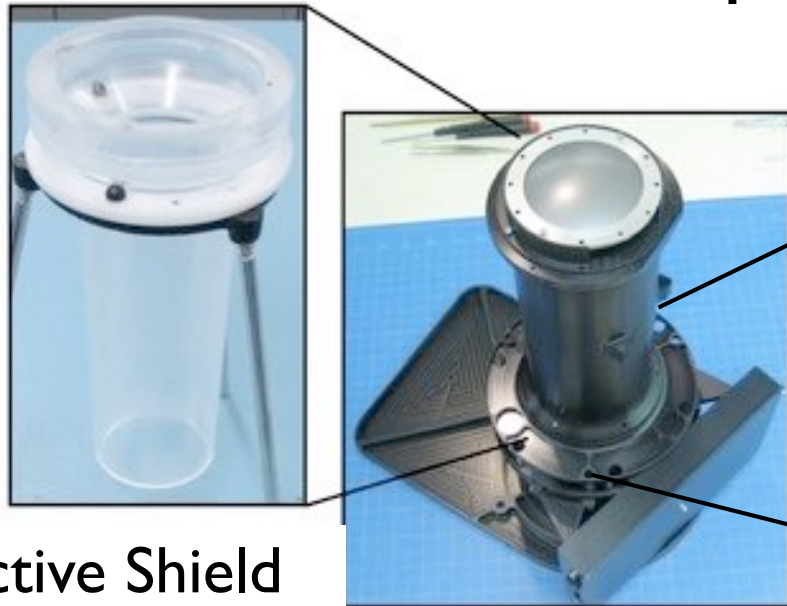
## DEPFET (MPE, PNSensor)



- It consists of a p-channel FET on a n-type bulk that is fully depleted by a reverse biased backside diode.
- WFI of ATHENA
- Pixel Size 130 $\mu$ m, Depletion 450 $\mu$ m
- Parallel readout at 1-5 $\mu$ sec/row, time resolution 5msec for 1K $\times$ 1K pixels
- ENC  $\sim$ 2-2.5 e (rms)

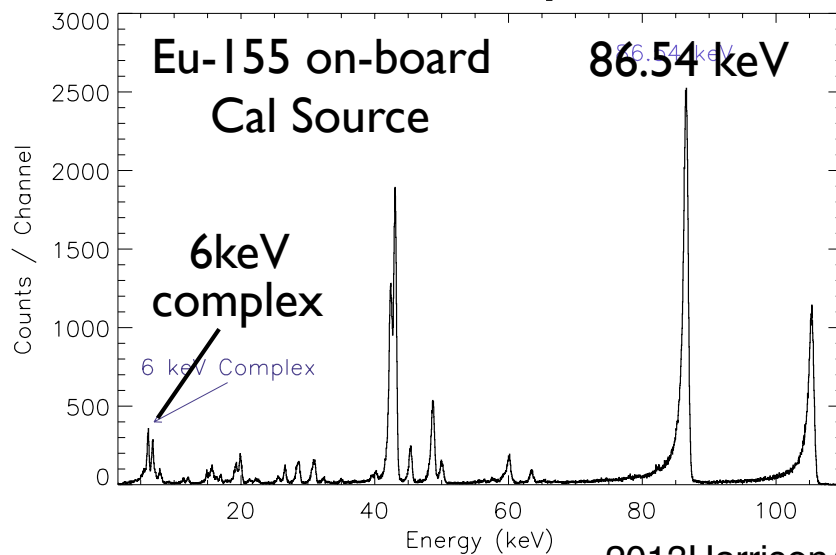


# CdZnTe pixel of NuSTAR

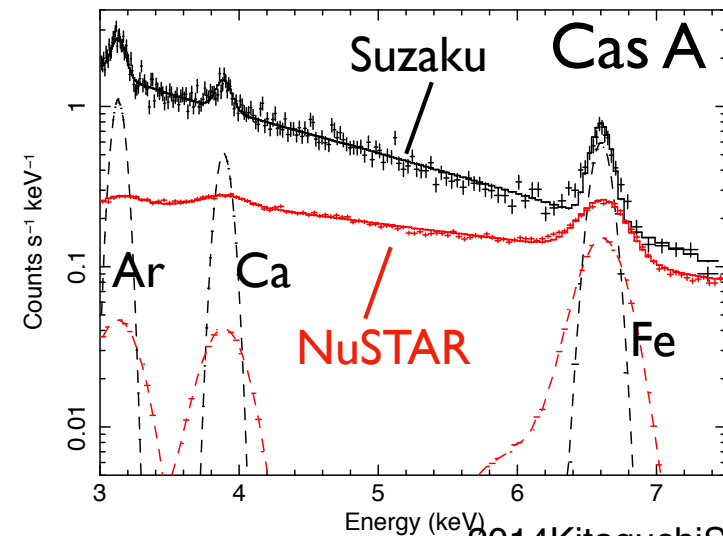


## CsI Active Shield

- Thickness 2mm, 20mm×20mm
- 605 $\mu\text{m}^2$ , 32×32 pixels
- Time resolution of 2 $\mu\text{sec}$
- Low noise by small input capacitance
- $\Delta E$  600eV at 6keV, 1keV at 60keV
- Lower E threshold of 2keV



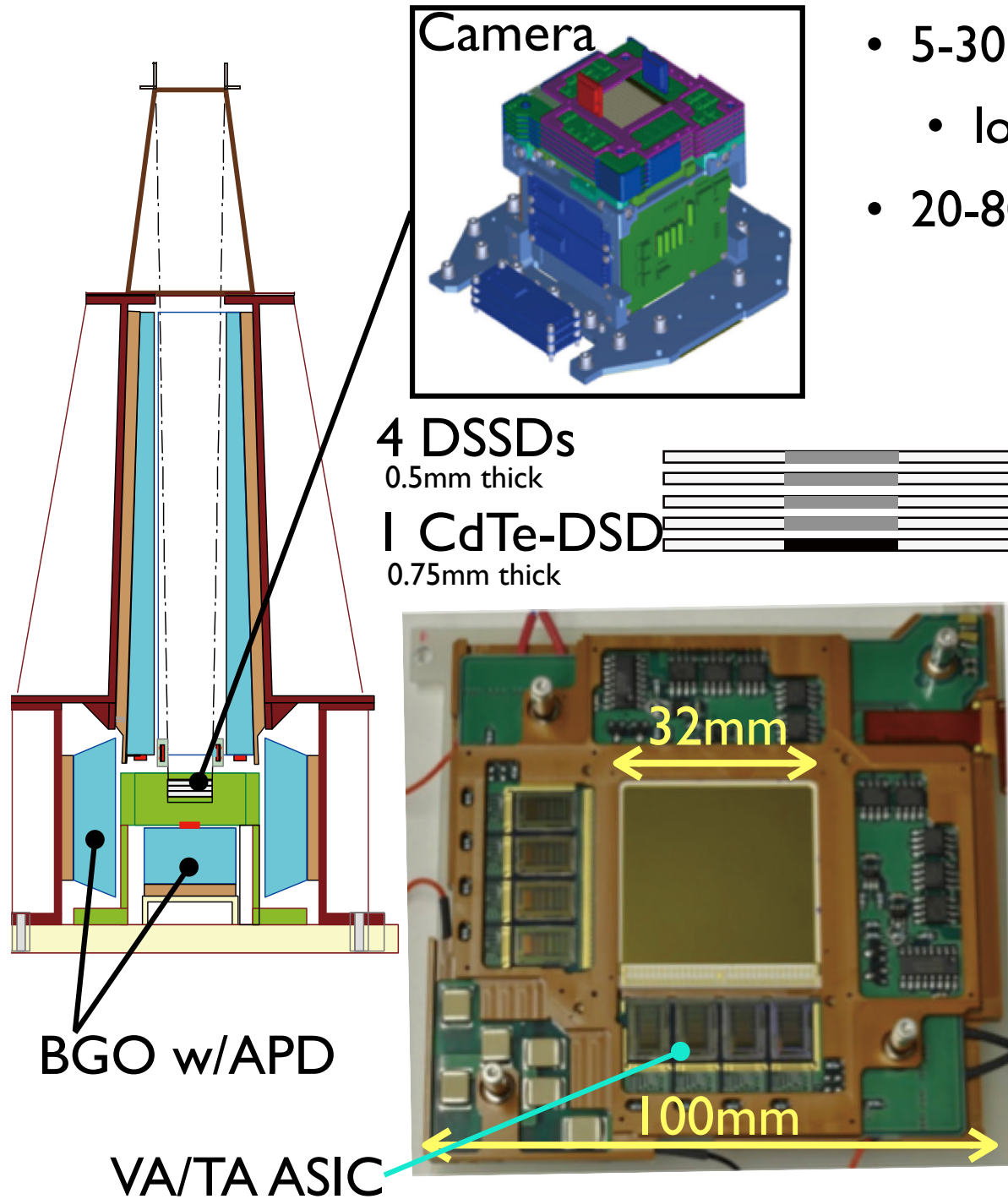
2013HarrisonApJ.pdf



2014KitaguchiSPIE.pdf

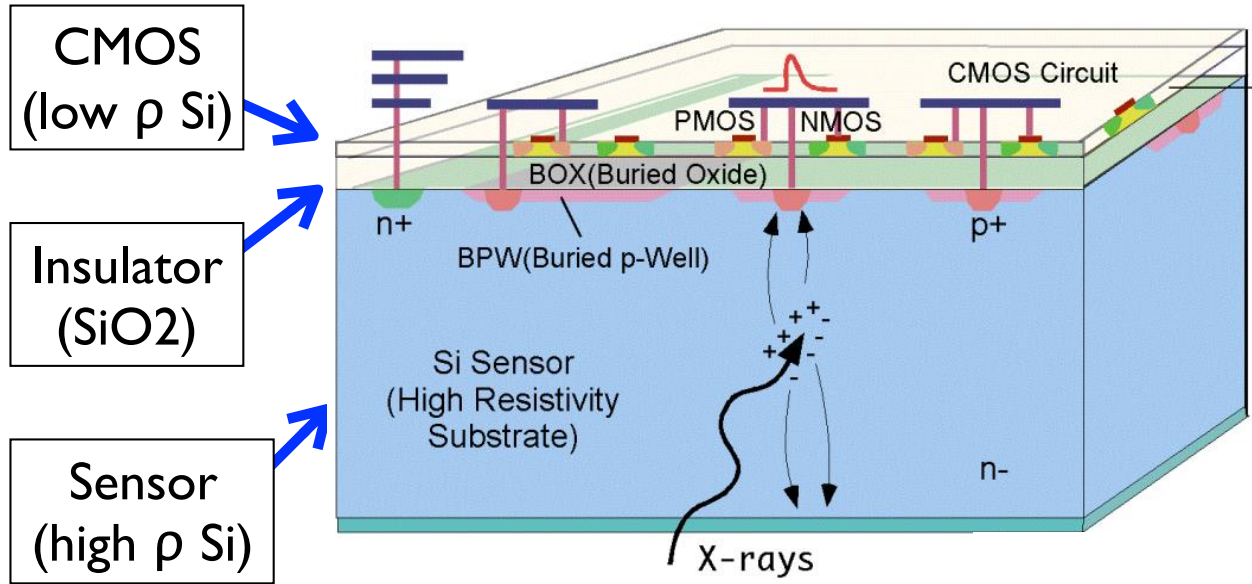


# HXI (DSSD + CdTe-DSD) of Hitomi



- 5-30keV by 4 DSSDs 0.5mm thick
  - low BGD by no activation
- 20-80keV by CdTe-DSD 0.75mm thick
  - Strip type
  - Larger input capacitance than a pixel type, which is a disadvantage for spectroscopy
  - Fine pitch (small pixel size) with smaller number of channels is available
  - 250 $\mu\text{m}$  for CdTe-DSD for Hitomi. 60 $\mu\text{m}$  for FOXSI-3 (see talk by Furukawa-san)
  - No dead structure including ASIC below sensor. Compton camera by stacking the sensors.

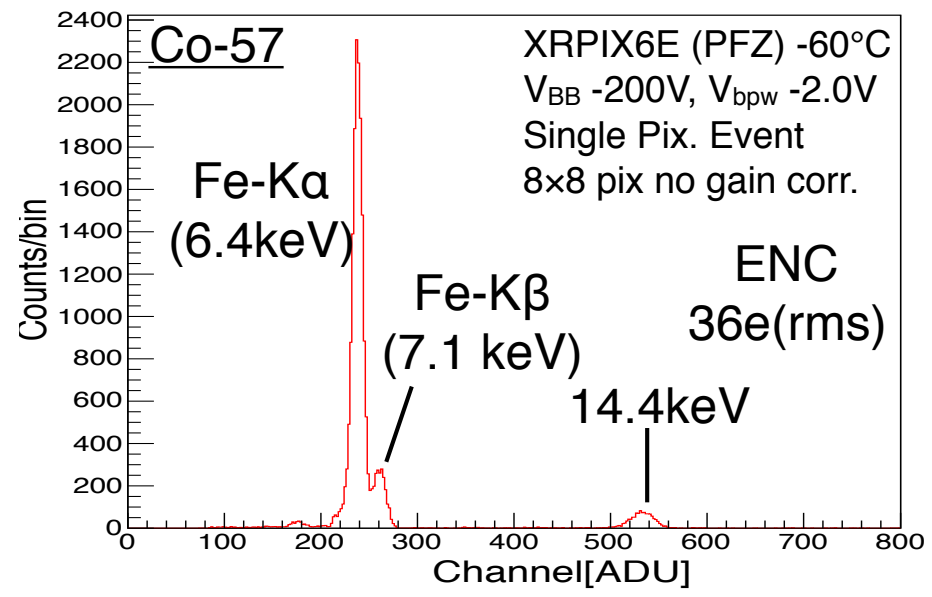
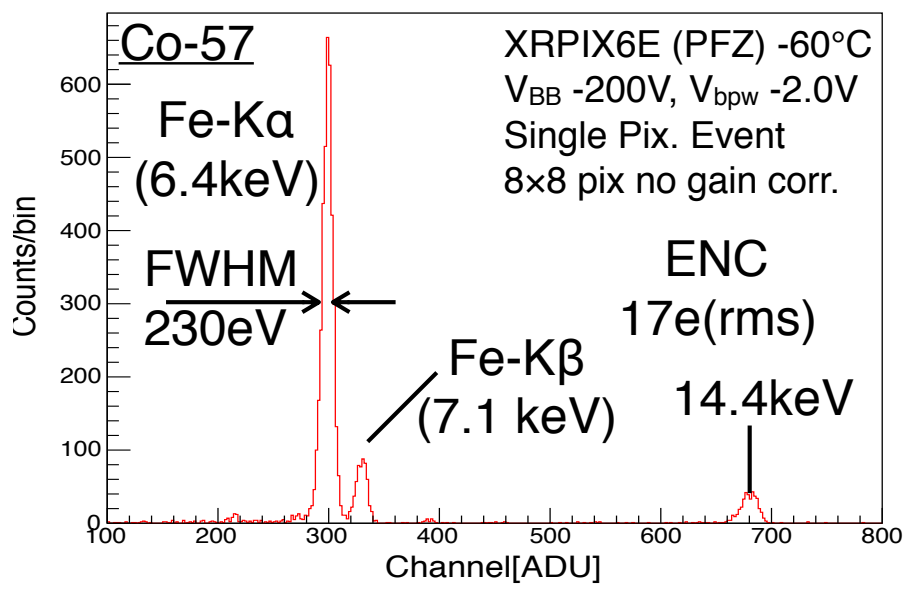
# X-ray SOIPIX (Kyoto/Miyazaki/KEK/Shizuoka/TUS)



- Each pixel has its own trigger logic and analogue readout CMOS circuit.
- Using trigger function and Readout hit pixel only.
- Time resolution  $\sim 1\mu\text{sec}$  and throughput  $\sim 1\text{kHz}$
- BI with depletion  $>200\mu\text{m}$

**Frame** readout mode

**Event-Driven** readout mode



See also talks by Kawahito-sensei, Arai-sense, Mori-sani, Onuki-san, Kamiya-san.  
posters by Takeda-san, Hayashi-san, Harada-san, Yarita-san, Negishi-san.



# Imaging in Event-Driven Mode

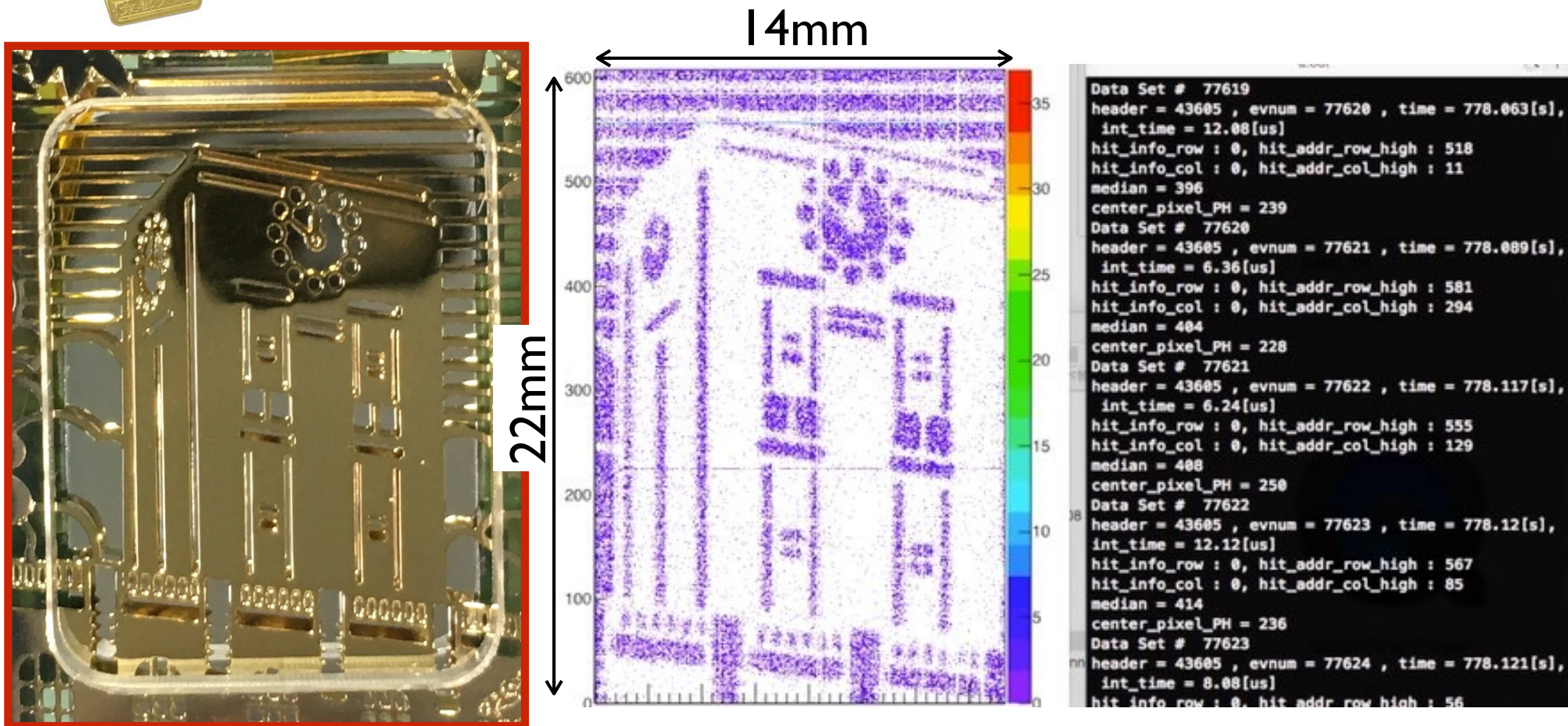


透かし彫り葉/金

SIZE:W35×H85mm

◆純金表面加工◆時計台を透かし彫りにした実用性の高いアイテムです。 **860** 円

<https://www.u-coop.net/kyodai/goods/indicate.php?mode=detail&id=27&category=6>



Cd-109,  $V_{bb}=10V$ , Room Temp. (movie in 10 times speed)

Capability of event rate  $> 500Hz$  is Confirmed

# Summary

- The conventional type of MOS-CCD is the standard imaging spectrometer in the energy band above 10 keV.
- Fast time resolution and fast readout is the key issues for the next generation of imagers.
- PNCCD, Digital CCD, Monolithic CMOS, Hybrid, DEPFET, X-ray SOIPIX.
- CdTe/CZT pixel and double-side strip detectors have been developed and used in the energy band above 10 keV.